

/ Descriptions

TO-220F

Schottky Diode in a TO-220F Plastic Package.

/ Features

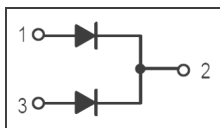
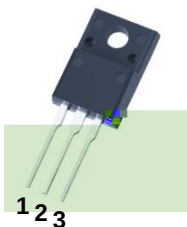
Low forward voltage drop, low power losses, High efficiency operation.

/ Applications

OR-ing

DC-DC

For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and reverse battery protection.

/ Equivalent Circuit**/ Pinning**

PIN1 Anode PIN 2 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

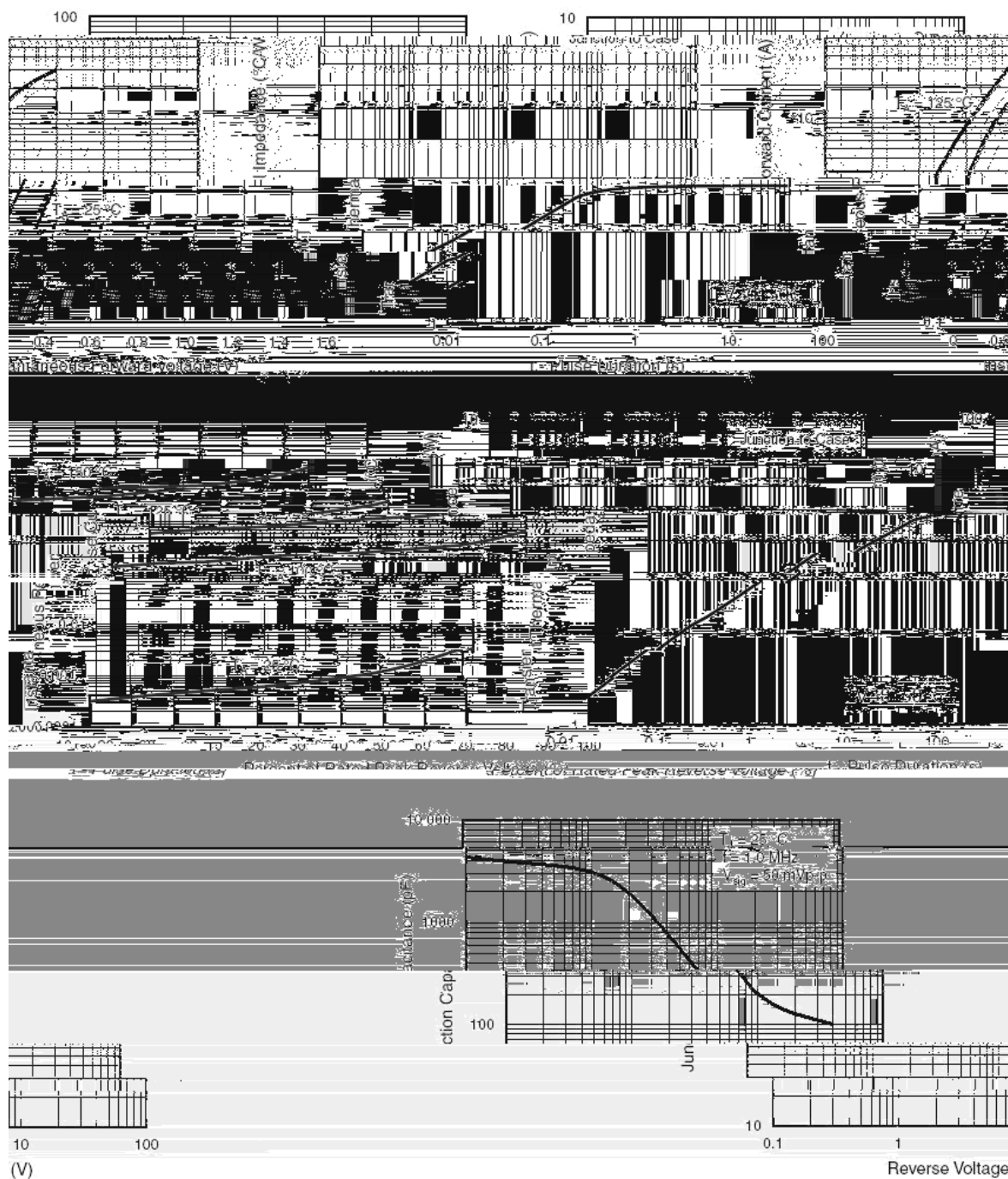
See Marking Instructions.

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RM} V_{RSM} V_{DC}	150	V
RMS Voltage	V_{RMS}	105	V
Average Rectified Forward Current(total)	$I_{F(AV)}$	2×15	A
Non Repetitive Peak Surge Current	I_{FSM}	250	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	4.6	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40 +150	

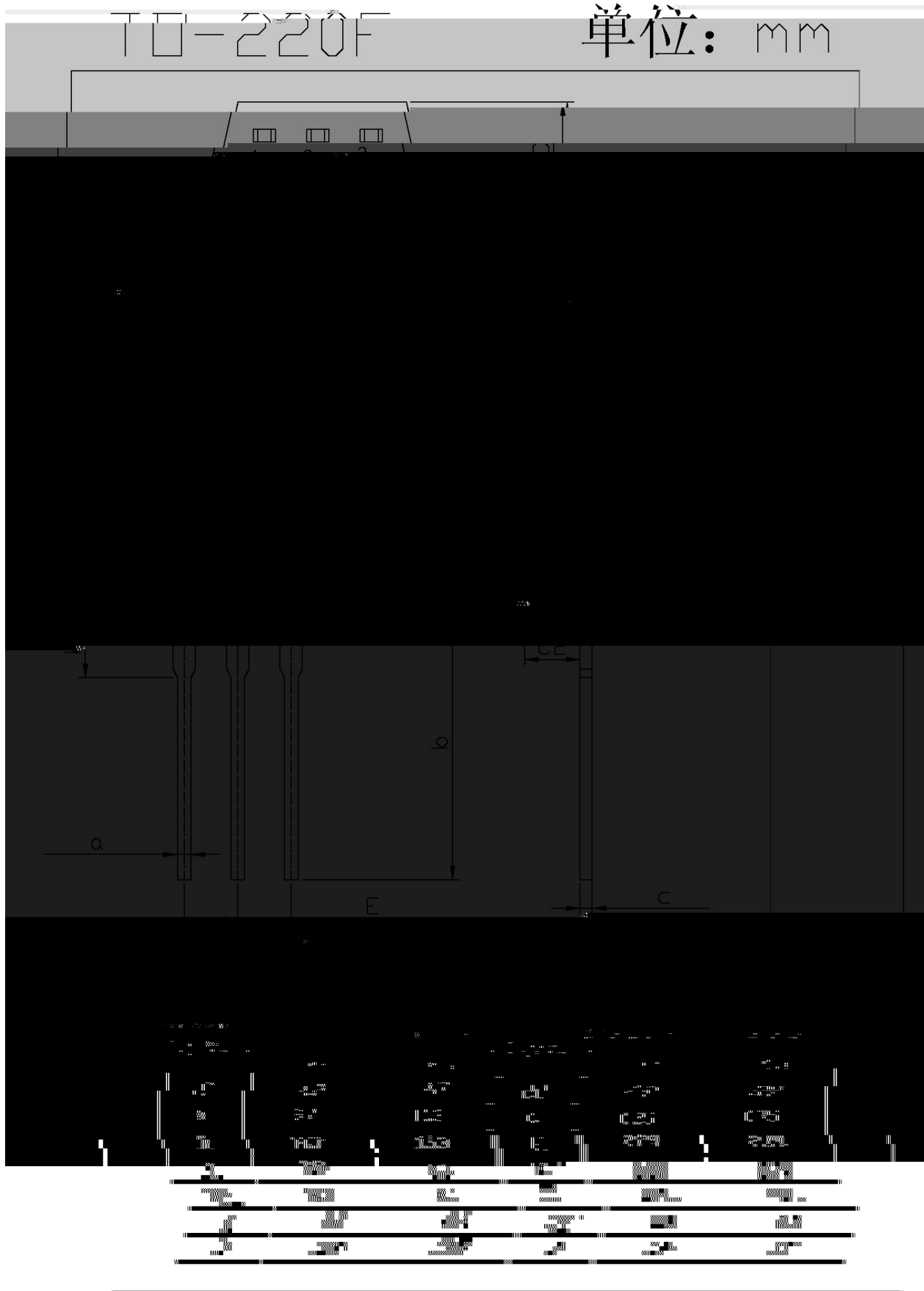
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown Voltage	V_{BR}	$I_R=1mA(T_a=25^\circ C)$	150			V

/3998 18.478())TJ/TT 1refV.3(V5 402.328 452.2.328 13-00013 Tc0.00307.02 0 0 7.5 292.32 453.8003 T400140013

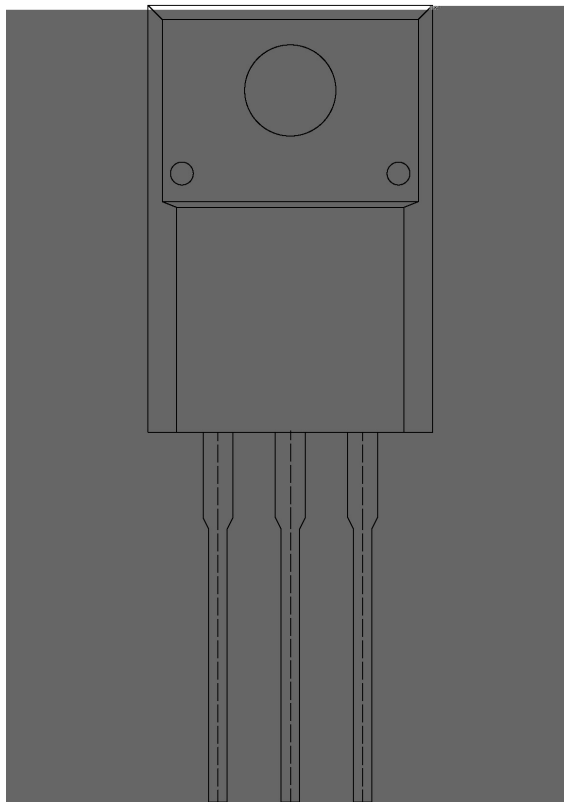
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



BR

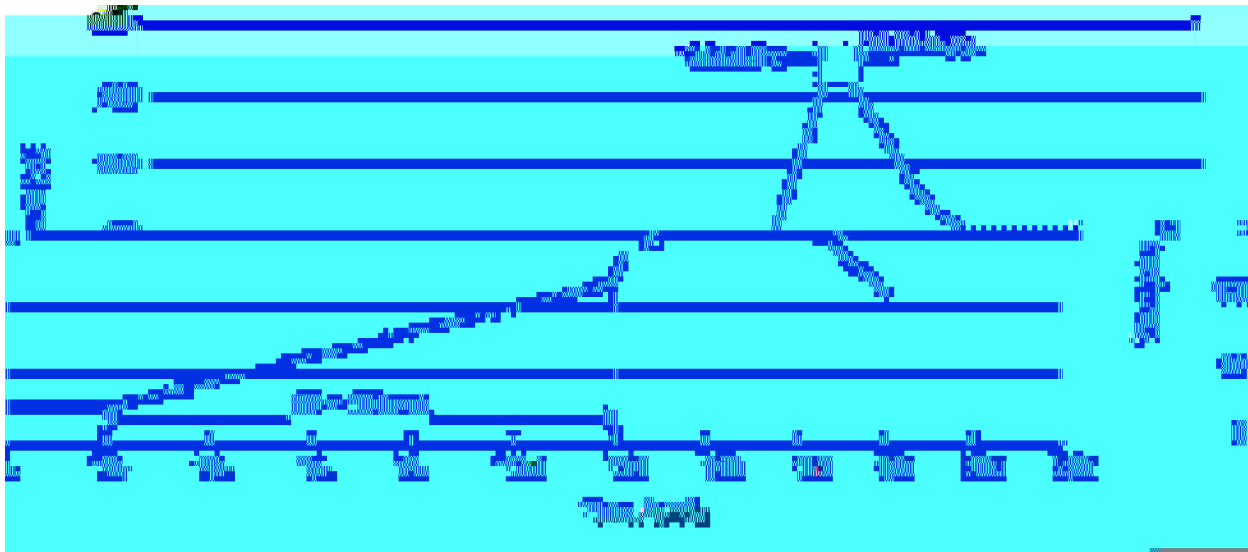
LV30150

F:

CT:

Note:

BR: Company Code


() / Temperature Profile for Dip Soldering(Pb-Free)


Note:

- 1 25 150 60 90sec;
- 2 255±5 5±0.5sec;
- 3 2 10 /sec.

- 1.Preheating:25~150 , Time:60~90sec.
- 2.Peak Temp.:255±5 , Duration:5±0.5sec.
3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5

10±1 sec.

Temp.:270±5

Time:10±1 sec

/ Packaging SPEC.
/ BULK

Package Type	Units					Dimension			(unit mm ³)

/ TUBE

Package Type	Units					Dimension			(unit mm ³)

/ Notices